



DMN33D8L

N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(ON)} max	I _D max T _A = +25°C
30V	3.0Ω @ $V_{GS} = 10V$	250mA
	3.8Ω @ V _{GS} = 5V	200mA

Description and Applications

This MOSFET has been designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Motor Control
- Power Management Functions
- Backlighting

Features and Benefits

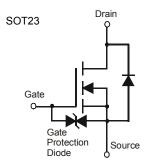
- Low On-Resistance
- Low Input Capacitance
- · Fast Switching Speed
- Low Input/Output Leakage
- ESD Protected 2KV
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

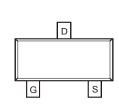
Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin annealed over Alloy 42
 Leadframe. Solderable per MIL-STD-202, Method 208³
 Weight: 0.008 grams (approximate)









Top View

Equivalent Circuit

Top View

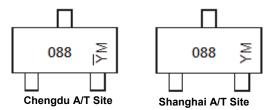
Ordering Information (Note 4)

Part Number	Compliance	Case	Packaging
DMN33D8L-7	Standard	SOT23	3000/Tape & Reel
DMN33D8L-13	Standard	SOT23	10000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



088 = Product Type Marking Code

YM = Date Code Marking for SAT (Shanghai Assembly/ Test site)

YM = Date Code Marking for CAT (Chengdu Assembly/ Test site)

Y or \overline{Y} = Year (ex: A = 2013)

M = Month (ex: 9 = September)

Date Code Key

Year	201	4	2015		2016	20	17	2018		2019	2	2020
Code	В		С		D	-	Ξ	F		G		Н
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units	
Drain-Source Voltage		V_{DSS}	30	V	
Gate-Source Voltage		V_{GSS}	±20	V	
Continuous Drain Current (Note 6) V _{GS} = 10V	Steady State	T _A = +25°C T _A = +70°C	I _D	250 200	mA
Continuous Drain Current (Note 6) $V_{GS} = 5V$ Steady $T_A = +25^{\circ}C$ State $T_A = +70^{\circ}C$			I _D	200 150	mA
Maximum Continuous Body Diode Forward Current	I _S	0.5	Α		
Pulsed Drain Current (10µs pulse, duty cycle = 1%	I _{DM}	0.8	А		

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units	
Total Power Dissipation (Note5)		P_D	350	mW
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{ heta JA}$	357	°C/W
Total Power Dissipation (Note 6)		P _D	520	mW
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{ heta JA}$	240	°C/W
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C

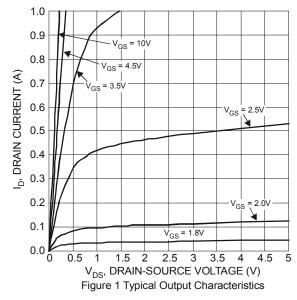
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

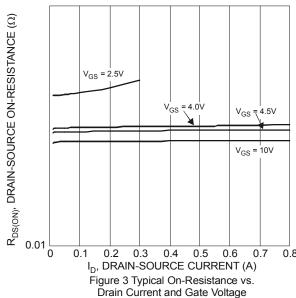
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	30	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current	I _{DSS}	_	_	1.0	μA	V _{DS} = 30V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	_	_	±10	μA	$V_{GS} = \pm 20V$, $V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(th)}	1.0	_	2.5	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$
Static Drain-Source On-Resistance	D		_	3.0	Ω	V _{GS} = 10V, I _D = 100mA
Static Dialit-Source Off-Resistance	R _{DS(ON)}	_	—	3.8	5.2	V_{GS} = 5V, I_D = 10mA
Forward Transfer Admittance	Y _{fs}	80	_	_	ms	V _{DS} =10V, I _D = 0.2A
Diode Forward Voltage	V _{SD}	_	0.75	1.1	V	V _{GS} = 0V, I _S = 115mA
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C _{iss}	_	50	_	pF	
Output Capacitance	C _{oss}	_	12	_	pF	V _{DS} = 15V, V _{GS} = 0V f = 1.0MHz
Reverse Transfer Capacitance	C _{rss}	_	10	_	pF	1.00012
Total Gate Charge	Qg	_	1.2	_	nC	401/1/
Gate-Source Charge	Q _{gs}	_	0.2	_	nC	$V_{GS} = 10V, V_{DS} = 10V,$ $I_{D} = 250mA$
Gate-Drain Charge	Q _{gd}	_	0.1	_	nC	ID - 20011M
Turn-On Delay Time	t _{D(on)}	_	2.3	_	ns	
Turn-On Rise Time	t _r	_	3.8	_	ns	$V_{DD} = 30V$, $I_D = 0.2A$, $V_{GEN} = 10V$,
Turn-Off Delay Time	t _{D(off)}	_	17.6	_	ns	$R_{GEN} = 25\Omega$
Turn-Off Fall Time	t _f	_	16.2	_	ns	

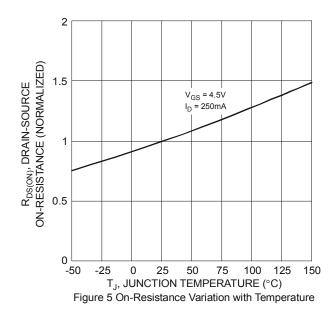
Notes:

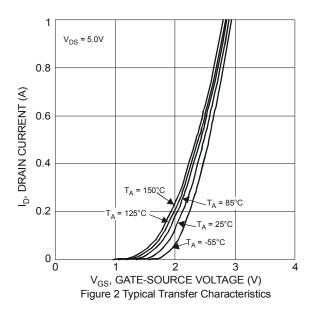
- Device mounted on FR-4 PCB, with minimum recommended pad layout
 Device mounted on 1" x 1" FR-4 PCB with high coverage 2oz. Copper, single sided.
 Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing.

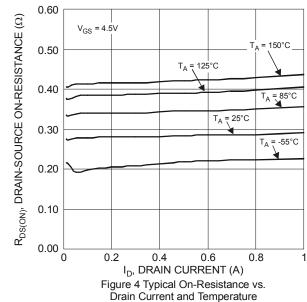


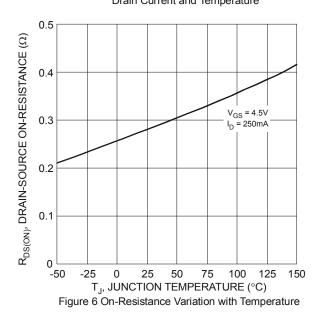














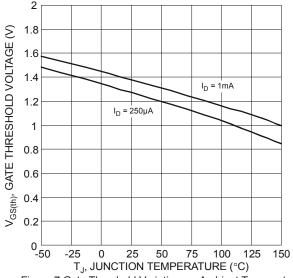
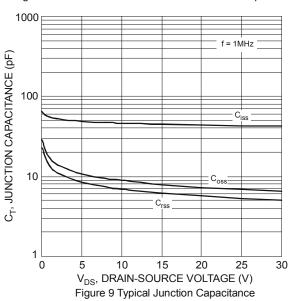
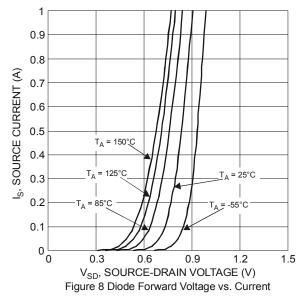
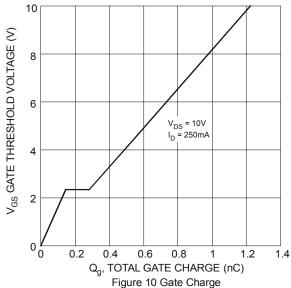


Figure 7 Gate Threshold Variation vs. Ambient Temperature

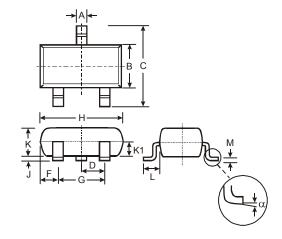






Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

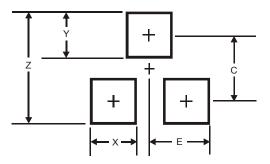


SOT23								
Dim	Min	Max	Тур					
Α	0.37	0.51	0.40					
В	1.20	1.40	1.30					
C	2.30	2.50	2.40					
D	0.89	1.03	0.915					
F	0.45	0.60	0.535					
G	1.78	2.05	1.83					
Η	2.80	3.00	2.90					
J	0.013	0.10	0.05					
K	0.903	1.10	1.00					
K1	-	-	0.400					
١	0.45	0.61	0.55					
М	0.085	0.18	0.11					
α	0°	8°	-					
All	Dimens	ions in	mm					



Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	2.9
Х	0.8
Υ	0.9
С	2.0
E	1.35

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